



1. The first step in the process of creating a new product is to identify a market need. This involves conducting market research to understand what consumers want and what problems they are facing. Once a need is identified, the next step is to develop a concept for a product that addresses that need. This is often done through brainstorming sessions with a team of designers and engineers. The concept is then refined through prototyping and testing. Once a viable concept is developed, the next step is to create a business plan that outlines the costs of production, the pricing strategy, and the marketing plan. Finally, the product is manufactured and distributed to the market. The entire process is iterative, with feedback from customers and sales data being used to refine the product and the business plan over time.

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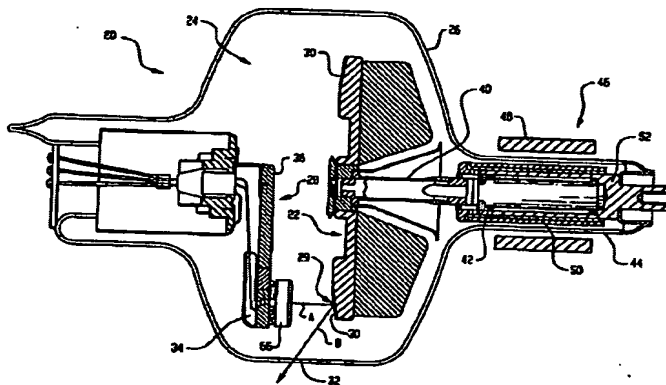
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 (71) Applicant (for all designated States except US): **KONINKLIJKE PHILIPS ELECTRONICS N.V. [NL/NL];**  
 Groenewoudseweg 1, NL-5621 BA Eindhoven (NL).  
 (72) Inventors; and  
 (75) Inventors/Applicants (for US only): **XU, Paul, M. [US/US];** 595 Miner Road, Cleveland, OH 44143 (US).  
**AWAD, George [US/US];** 595 Miner Road, Cleveland, OH 44143 (US).  
**PERNO, Salvatore, G. [US/US];** 595 Miner Road, Cleveland, OH 44143 (US).  
**LU, Qing, K. [US/US];** 595 Miner Road, Cleveland, OH 44143 (US).  
 (74) Common Representative: **KONINKLIJKE PHILIPS ELECTRONICS N.V.;** c/o Lundin, Thomas, M., 595 Miner Road, Cleveland, OH 44143 (US).  
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(54) Title: X-RAY TUBE CATHODE ASSEMBLY AND INTERFACE REACTION JOINING PROCESS



(57) **Abstract:** An x-ray tube cathode assembly (28) includes a support arm (36) comprising a first metal. A ceramic insulator (70, 82) has a first metalized surface (72, 86) wherein the metalized surfaces comprise a desired amount of the first metal. A first member of filler material (90) is in contact with the support arm (36) and the first metalized surface (72, 86) of the ceramic insulator (70, 82), the first member of filler material comprising at least a second metal (96a, 96b) wherein a first alloy system (Fig. 5) comprising the first and second metals includes an alloy minimum point percentage composition (P) of the first and second metals having a first alloy system minimum melting point (M) for the alloy minimum point percentage composition that is lower than both of the melting point of the first metal and second metal. A bonding region resulting from heating the cathode assembly causing diffusion bonding to proceed, the bonding region has a layer of alloy comprising the minimum point percentage composition (P) and the heating of the cathode assembly continues to a bonding temperature of at least the first alloy system minimum melting point (M) and holding at that temperature for a desired period of time.

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